

N-Channel MOSFET

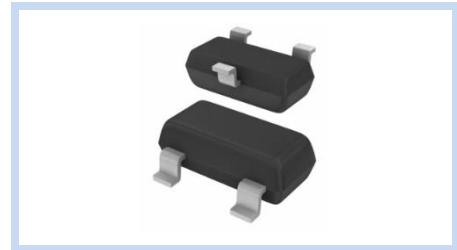
60V 360mA 0.35W SOT-23 ESD

MFT6NA36S23E

MERITEK

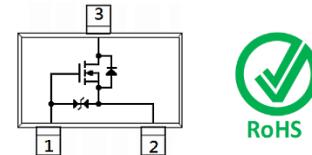
FEATURE

- $R_{DS(ON)}=1.6\Omega$, $V_{GS}=10V$, $I_D=350mA$
- $R_{DS(ON)}=2.2\Omega$, $V_{GS}=4.5V$, $I_D=200mA$
- $R_{DS(ON)}=6.5\Omega$, $V_{GS}=2.2V$, $I_D=10mA$
- ESD Protection >2kV
- Application: Power Management in Notebook, Battery Powered System



MECHANICAL DATA

- Case: SOT-23 Package
- Terminals: Solderable per MIL-STD-750, Method 2026

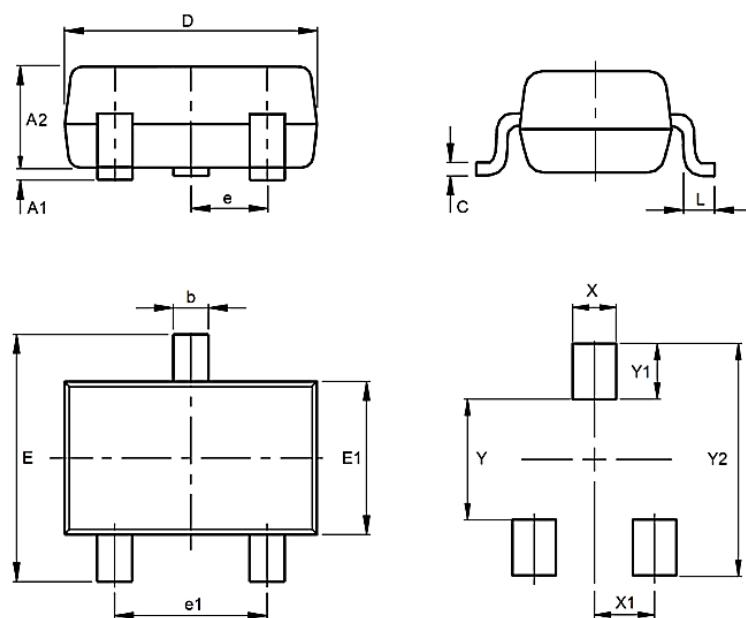


MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current – Continuous	I_D	360	mA
$V_{GS}=10V, T_A=25^\circ C$		230	
Drain Current – Pulsed	I_{DM}	1.2	A
Power Dissipation	P_D	350	mW
(Note 5)		420	
(Note 4)			
Operating and Storage Temperature Range	T_J, T_{stg}	-55 to 150	°C
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	370	°C / W
(Note 5)		300	
(Note 4)			

DIMENSIONS

SOT-23	Min (mm)	Max (mm)
A1	0.00	0.10
A2	0.79	1.40
b	0.30	0.50
c	0.08	0.20
D	2.70	3.10
e	0.955 TYP	
e1	1.78	2.04
E	2.10	2.80
E1	1.20	1.60
L	0.15	--
X	0.80	
X1	0.95	
Y	1.40	
Y1	1.00	
Y2	3.40	



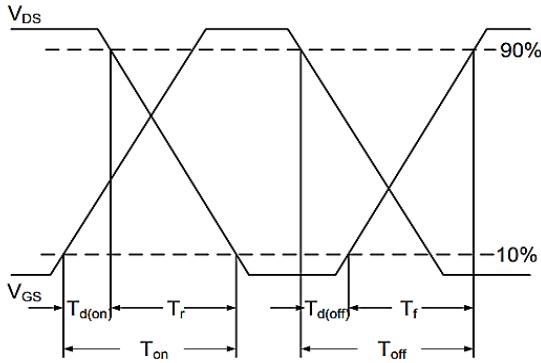
ELECTRICAL CHARACTERISTICS

Off Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D= 250\mu A$	BV_{DSS}	60	--	--	V
Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D= 250\mu A$	$V_{GS(th)}$	0.48	--	1.6	V
Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 10V$	I_{GS}	--	--	± 1	μA
	$V_{DS}=0V, V_{GS}=\pm 20V$		--	--	± 10	
Zero Gate Voltage Drain Current	$V_{DS}= 60V, V_{GS}=0V$	I_{DSS}	--	--	1	μA
On Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Static Drain-Source On-Resistance	$V_{GS}= 10V, I_D= 350mA$	$R_{DS(on)}$	--	--	1.6	Ω
	$V_{GS}= 4.5V, I_D= 200mA$		--	--	2.2	
	$V_{GS}= 2.5V, I_D= 10mA$		--	--	6.5	
Dynamic Characteristics	Conditions	Symbol	--	Typ.	Max	Unit
Input Capacitance	$V_{DS}= 10V, V_{GS}=0V$ $F=1.0MHz$	C_{iss}	--	--	56	pF
Output Capacitance		C_{oss}	--	7	--	
Reverse Transfer Capacitance		C_{rss}	--	4	--	
Turn-On Delay Time	$V_{DS}= 10V, I_D \geq 1A,$ $V_{GS}= 4.5V, R_G= 51\Omega$	$T_{d(on)}$	--	--	10	nS
Rise Time		T_r	--	5	--	
Turn-Off Delay Time		$T_{d(off)}$	--	7.8	76	
Fall Time		T_f	--	20	--	
Drain-Source Body Diode	Conditions	Symbol	Min	Typ.	Max	Unit
Diode Forward Voltage	$I_S= 0.3A, V_{GS}=0V$	V_{SD}	0.47	--	1.2	V
Forward Transconductance	$V_{DS}= 10V, I_D= 200mA$	g_{fs}	--	0.7	--	S

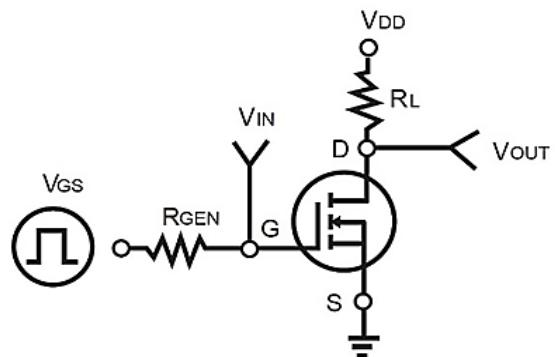
Notes:

1. $T_A = 25^\circ C$ Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability
2. Pulse width < 300μs, Duty cycle < 2%.
3. $R_{\Theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins mounted on a PCB described in Note 4&5.
4. Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm².
5. Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

Switching Time Waveform



Switching Test Circuit



CHARACTERISTIC CURVES

